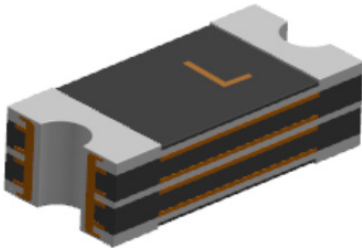


# Resettable PPTC Fuses - 1206 multicomp<sup>PRO</sup>

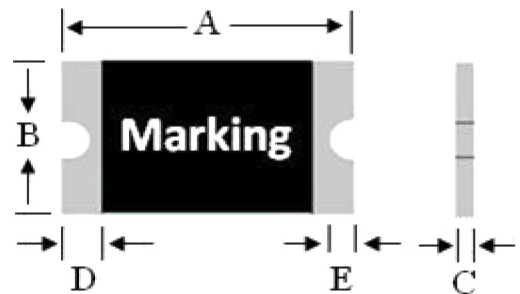
RoHS  
Compliant



## Features

- Fast tripping, 1206 Size
- Surface mountable, Solid state
- Holding Current: 4A to 6A, @25°C
- Maximum Voltage: 6V and 12V
- Operating Temperature: -40°C to +85°C
- Agency Approvals: UL E345393, TUV R50449459

Dimensions : Millimetres



Part NO.	Marking	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
MP005228	L	3	3.5	1.5	1.8	0.5	1.1	0.25	0.1
MP005229									
MP005230	M					0.6	1.4		
MP005231									
MP005232	N					0.7			
MP005233									
MP005234	R								
MP005235									

## Electrical Specifications

Part NO.	V <sub>MAX</sub> (V)	I <sub>MAX</sub> (A)	I <sub>H</sub> (A)	I <sub>T</sub> (A)	P <sub>D</sub> (W)	Maximum Time-to-Trip		Resistance	
						Current	Time	R <sub>MIN</sub>	R <sub>1MAX</sub>
						(A)	(Sec)	(Ω)	(Ω)
MP005228	6	50	4	8	1.4	20	2	0.004	0.014
MP005229	12								
MP005230	6		4.5	9		22.5			
MP005231	12								
MP005232	6		5	10		25	2	0.002	0.011
MP005233	12								
MP005234	6		6	12		30	2	0.009	
MP005235	12								

Newark.com/multicomp-pro  
Farnell.com/multicomp-pro  
Element14.com/multicomp-pro

**multicomp<sup>PRO</sup>**

# Resettable PPTC Fuses - 1206 multicomp<sup>PRO</sup>

## Thermal Derating Chart-I<sub>H</sub> (A)

Part NO.	Maximum holding current at assigned ambient temperature (A)								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
MP005228	5.92	5.33	4.64	4	3.52	3.09	2.83	2.45	1.92
MP005229									
MP005230	6.66	6	5.22	4.5	3.96	3.48	3.17	2.76	2.16
MP005231									
MP005232	7.4	6.67	5.8	5	4.4	3.87	3.53	3.07	2.4
MP005233									
MP005234	8.65	7.91	6.93	6	5.23	4.45	4	3.63	2.85
MP005235									

## Physical Characteristics

Terminal Pad Materials	Tin-Plated Nickle-copper
Soldering Characteristics	EIA Specification RS 186-9E, ANSI/J-STD-002
Moisture Sensitivity	Level 2a, per IPC/JEDEC J-STD 020C

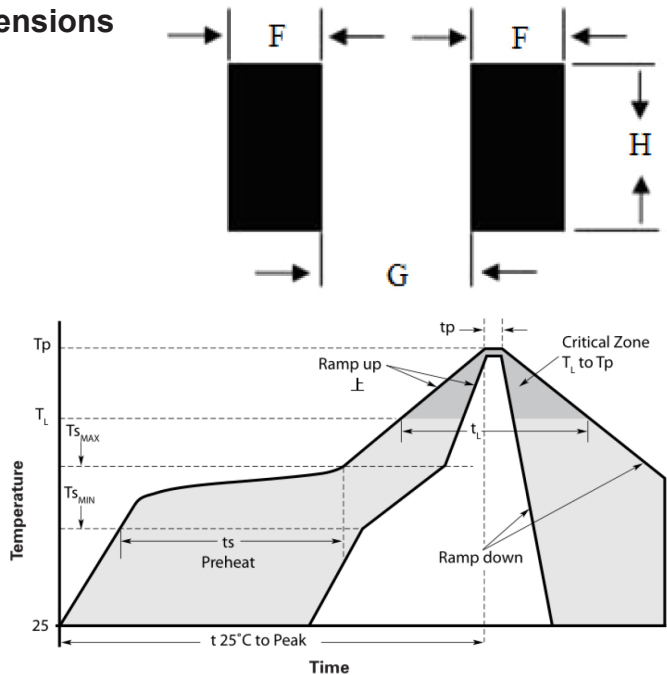
## Test Procedures And Requirements

Test Item	Test Conditions	Accept/Reject Criteria
Initial Resistance	In still air at 25°C	$R_{MIN} \leq R \leq R_{1MAX}$
Time to Trip	Specified current $V_{MAX}$ , 25°C	$t \leq$ Maximum Time to Trip
Holding Current	1 hour at $I_H$ , 25°C	No trip
Trip Endurance	$V_{MAX}$ , $I_{MAX}$ , 1 hour	No arcing or burning

# Resettable PPTC Fuses - 1206 multicomp<sup>PRO</sup>

## Solder Reflow Profiles And Pad Layout Dimensions

Solder pad layout Dimensions (mm)			
Normal Value	F	G	H
	1	1.8	1.8
<b>Profile Feature</b>	<b>Pb-Free</b>		
Average ramp up rate (T <sub>S</sub> MAX to T <sub>p</sub> ) 3°C/ max.			
Preheat			
• Temperature min (T <sub>S</sub> MIN) 150°C			
• Temperature max (T <sub>S</sub> MAX) 200°C			
• Time (t <sub>S</sub> MIN to t <sub>S</sub> MAX) 60 to 120 seconds			
Time maintained above			
• Temperature (T <sub>L</sub> ) 217°C			
• Time(t <sub>L</sub> ) 60 to 150 seconds			
Peak/Classification temperature (TP) 260°C			
Time within 5°C of actual peak temperature			
Time (t <sub>P</sub> ) 30 seconds max			
Ramp down rate 3°C/second max			
Time 25°C to peak temperature 8 minutes max			



Recommended reflow methods: IR, hot air oven, N2 environment for lead-free.

Devices are not designed to be wave soldered to the bottom side of the board.

Recommended maximum paste thickness is 0.25mm (0.01inch).

Devices can be cleaned using standard industry methods and aqueous solvents.

Devices can be reworked using the standard industry practices .Please also avoid direct contact to the device.

If reflow temperature exceed the recommended profile, devices may not meet the performance requirements.

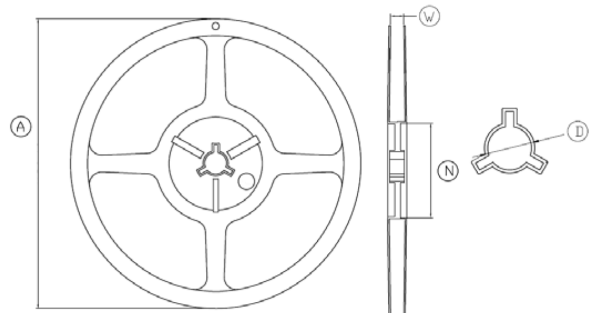
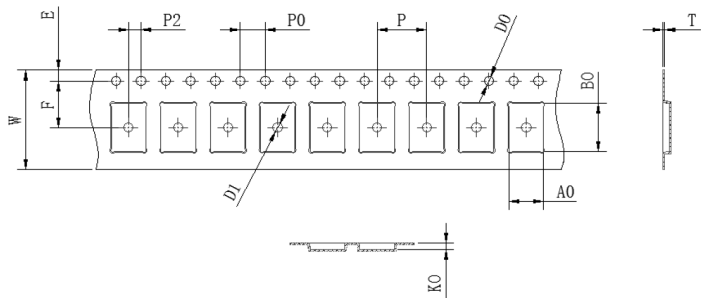
## Packing Information

### Tape Specifications

W	8 ±0.1
P0	4 ±0.1
P	4 ±0.1
P2	2 ±0.1
A0	1.9 ±0.1
B0	3.65 ±0.1
D0	1.5 +0.1/-0
D1	1 +0.1/-0
F	3.5 ±0.1
E	1.75 ±0.1
T	0.25 ±0.05
K0	0.87±0.1
	1.33±0.05
	1.7±0.1

### Reel Dimensions

A	178 ±1
D	13.3 ±0.3
W	8.5 +1/-0.2
N	59 ±1



Newark.com/multicomp-pro  
 Farnell.com/multicomp-pro  
 Element14.com/multicomp-pro

**multicomp<sup>PRO</sup>**

# Resettable PPTC Fuses - 1206 **multicomp**PRO

---

## Storage

The maximum ambient temperature shall not exceed 40°C. Storage temperatures higher than 40°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use

## Warning

- Use PPTC beyond the maximum ratings or improper use may result in device damage, electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Use PPTC with a large inductance in circuit will generate a circuit voltage above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.
- Users should independently evaluate the suitability of the product and test each product selected for their own application.

**Important Notice** : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for their purpose and not make any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

Newark.com/multicomp-pro  
Farnell.com/multicomp-pro  
Element14.com/multicomp-pro

**multicomp**PRO